What is claimed is:

1. Apparatus for detecting wafer flat shift, comprising:
a plurality of sensors in a power supply circuit for shutting off wafer fabrication equipment, the sensors detecting a shift in wafer flat position; and the power supply circuit shutting off the wafer fabrication equipment.

2. The apparatus of claim 1, further comprising:
the sensors being adjusted to detect a wafer flat shift in a plurality of directions of angular displacement.

3. The apparatus of claim 1, further comprising:
the sensors being adjusted to detect a wafer flat shift in a range of $(2)(0.9^0)$ to $(5)(0.9^0)$ angular displacement.

4. The apparatus of claim 1, further comprising:
a frame; and
an adjustable mounting mechanism mounting each of the sensors on the frame for adjustment along orthogonal axes.

5. The apparatus of claim 1, further comprising:
a frame; and
the sensors being adjustably mounted on the frame.

6. The apparatus of claim 1, further comprising:
a relay receiving signals from the sensors; and
a solenoid operated by the relay to open a door of the wafer fabrication equipment to release a corresponding wafer for further fabrication; and
a wafer flat shift shutting off at least one of the signals from the sensors.

7. A method of detecting wafer flat shift comprising the steps of;

detecting a wafer flat shift; and

shutting off a wafer fabrication equipment when the wafer flat shift exceeds a set amount.

8. The method as recited in claim 7, further comprising the step of:

detecting a wafer flat shift in a plurality of directions of angular displacement.

9. The method as recited in claim 7, further comprising the step of:

detecting the wafer flat shift by optical beam sensors.

10. The method as recited in claim 7, further comprising the step of:

detecting a wafer flat shift in a range of $(2)(0.9^0)$ to $(5)(0.9^0)$ angular displacement.

11. The method as recited in claim 7, further comprising the steps of:

detecting the wafer flat shift by optical beam sensors; and

adjusting the positions of the sensors.

12. The method as recited in claim 7, further comprising the steps of:

detecting the wafer flat shift by optical beam sensors;

sending signals from the sensors to a relay;

operating a solenoid by the relay to open a door of the wafer fabrication equipment to release a corresponding wafer for further fabrication; and

shutting off at least one of the signals from the sensors by the wafer flat shift.

13. The method as recited in claim 12, further comprising the step of:

detecting a wafer flat shift of $(2)(0.9^0)$ angular displacement.

14. The method as recited in claim 12, further comprising the step of:

detecting a wafer flat shift of $(5)(0.9^0)$ angular displacement.

15. A control circuit, comprising:

sensors to detect an edge of a wafer flat on a wafer;

a power supply supplying power to the sensors;

a relay activated by outputs of the sensors;

a solenoid activated by the relay to unlock a door for exit of the wafer to equipment for further wafer fabrication; and

at least one of the sensors sensing a wafer flat shift, which shuts off the equipment.

16. The control circuit of claim 15, further comprising:

the sensors being set to detect a wafer flat shift of $(2)(0.9^0)$ angular displacement.

17. The control circuit of claim 15, further comprising:

the sensors being set to detect a wafer flat shift of $(5)(0.9^0)$ angular displacement.

18. The control circuit of claim 15, further comprising:

the sensors being mounted for adjustment along orthogonal axes corresponding to the a wafer flat shift in angular displacement.

19. The control circuit of claim 15, further comprising:

the sensors being adjustable on the frame.

20. The control circuit of claim 15, further comprising:

the sensors being adjustable along orthogonal axes.